

Electronic Patent Application Fee Transmittal

Application Number:	10612222			
Filing Date:	03-Jul-2003			
Title of Invention:	Component-embedded board fabrication method and apparatus for high-precision and easy fabrication of component-embedded board with electronic components embedded in wiring board			
First Named Inventor/Applicant Name:	Masatoshi Akagawa			
Filer:	Aaron Colby Walker/Brian Formagus			
Attorney Docket Number:	300.1119			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810